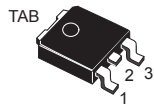
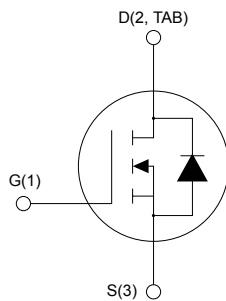


## N-channel 60 V, 32 mΩ typ., 24 A, STripFET II Power MOSFET in a DPAK package


**DPAK**


AM01475v1\_noZen

### Features

Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$	$P_{TOT}$
STD20NF06L	60 V	40 mΩ	24 A	60 W

- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

### Applications

- Switching applications

### Description

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.



#### Product status link

[STD20NF06L](#)

#### Product summary

<b>Order code</b>	STD20NF06LT4
<b>Marking</b>	D20NF06L
<b>Package</b>	DPAK
<b>Packing</b>	Tape and reel

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	60	V
$V_{GS}$	Gate-source voltage	±18	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	24	A
	Drain current (continuous) at $T_C = 100\text{ °C}$	17	
$I_{DM}^{(1)}$	Drain current (pulsed)	96	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ °C}$	60	W
	Derating factor	0.4	W/°C
$dv/dt^{(2)}$	Peak diode recovery voltage slope	10	V/ns
$E_{AS}^{(3)}$	Single pulse avalanche energy	225	mJ
$T_{stg}$	Storage temperature range	-55 to 175	°C
$T_J$	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2.  $I_{SD} \leq 24\text{ A}$ ,  $di/dt \leq 300\text{ A/ns}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$
3. Starting  $T_J = 25\text{ °C}$ ,  $I_D = I_{AR}\text{ A}$ ,  $V_{DD} = 45\text{ V}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	2.5	°C/W
$R_{thJB}^{(1)}$	Thermal resistance, junction-to-board	50	

1. When mounted on a 1-inch<sup>2</sup> FR-4, 2 Oz copper board.

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified).

**Table 3. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}, T_C = 125\text{ °C}^{(1)}$			10	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 18\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1		2.5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 12\text{ A}$		32	40	m $\Omega$
		$V_{GS} = 5\text{ V}, I_D = 12\text{ A}$			50	

1. Defined by design, not subject to production test.

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}$	Forward transconductance	$V_{DS} = 25\text{ V}, I_D = 12\text{ A}$	-	20	-	S
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	660	-	pF
$C_{oss}$	Output capacitance		-	170	-	pF
$C_{riss}$	Reverse transfer capacitance		-	70	-	pF
$t_{d(on)}$	Turn-on delay time		-	11	-	ns
$t_r$	Rise time	$V_{DD} = 30\text{ V}, I_D = 10\text{ A}, R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see Figure 11. Test circuit for resistive load switching times)	-	50	-	ns
$t_{d(off)}$	Turn-off delay time		-	20	-	ns
$t_f$	Fall time		-	12	-	ns
$Q_g$	Total gate charge	$V_{DD} = 30\text{ V}, I_D = 20\text{ A}, V_{GS} = 10\text{ V}, R_G = 4.7\text{ }\Omega$ (see Figure 12. Test circuit for gate charge behavior)	-	13	-	nC
$Q_{gs}$	Gate-source charge		-	3.5	-	nC
$Q_{gd}$	Gate-drain charge		-	8	-	nC

**Table 5. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		24	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		96	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 20\text{ A}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 20\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 20\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$ (see Figure 13. Test circuit for inductive load switching and diode recovery times)	-	56		ns
$Q_{rr}$	Reverse recovery charge		-	108		nC
$I_{RRM}$	Reverse recovery current		-	4		A

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

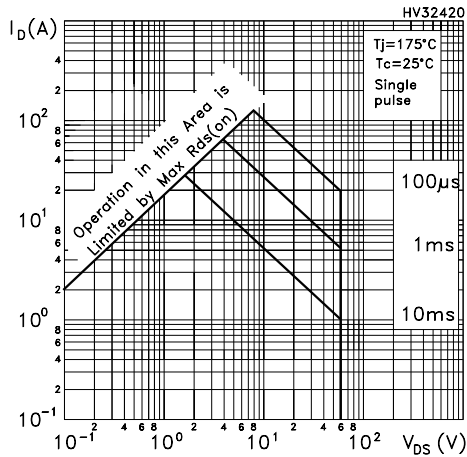


Figure 2. Thermal impedance

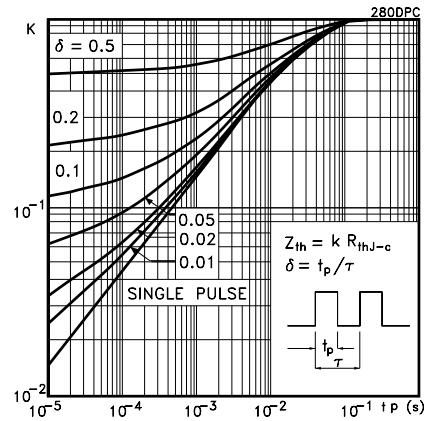


Figure 3. Output characteristics

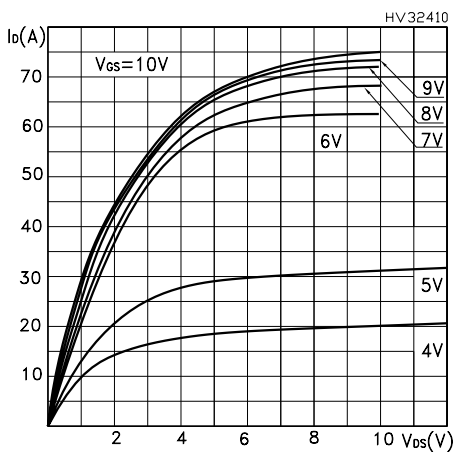


Figure 4. Transfer characteristics

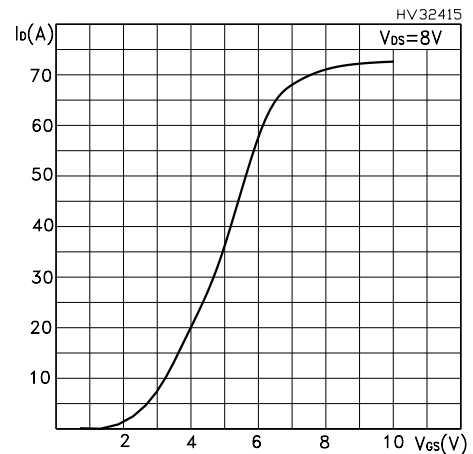


Figure 5. Static drain-source on-resistance

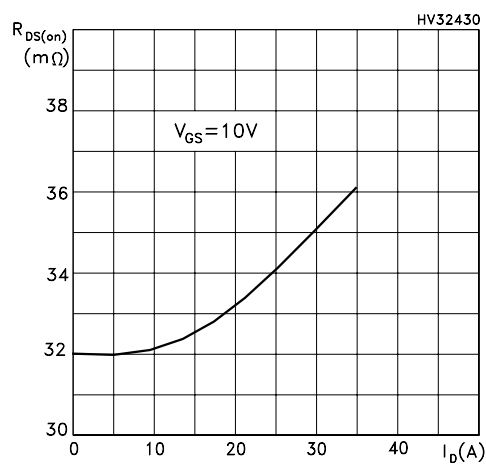
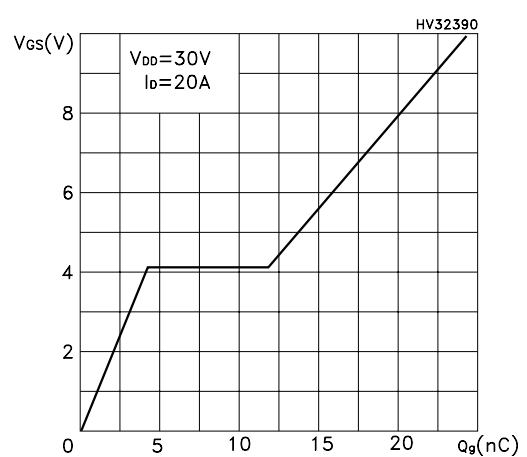
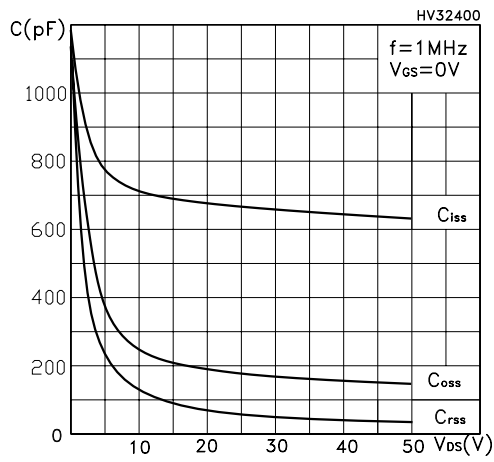


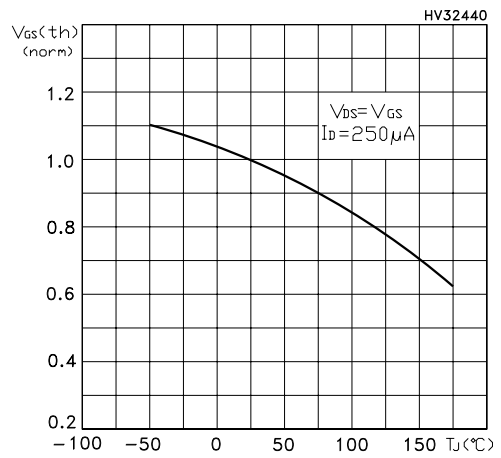
Figure 6. Gate charge vs gate-source voltage



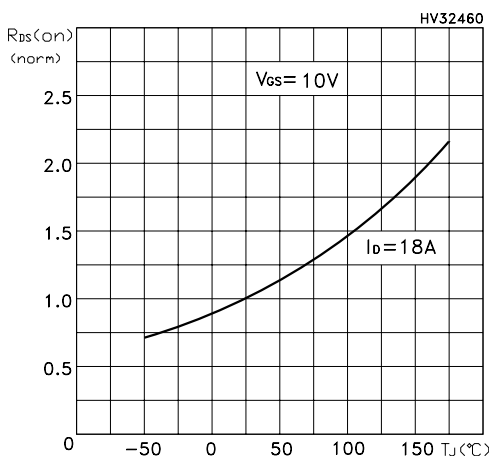
**Figure 7. Capacitance variations**



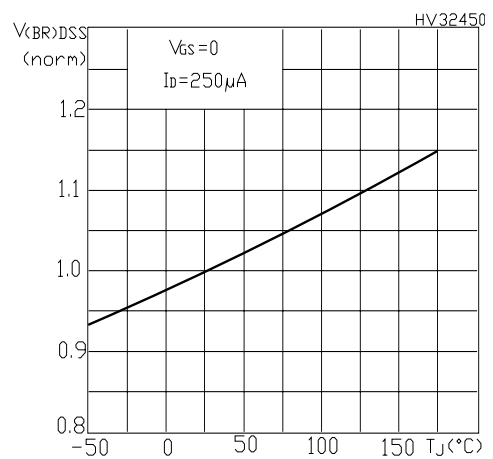
**Figure 8. Normalized gate threshold voltage vs temperature**



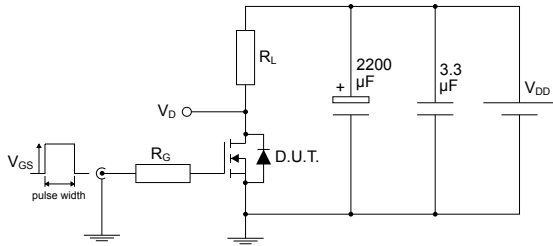
**Figure 9. Normalized on-resistance vs temperature**



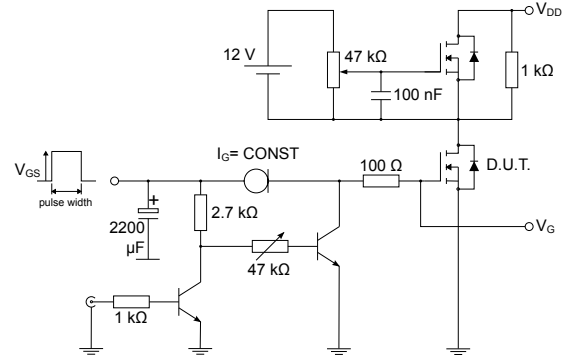
**Figure 10. Normalized V<sub>(BR)DSS</sub> vs temperature**



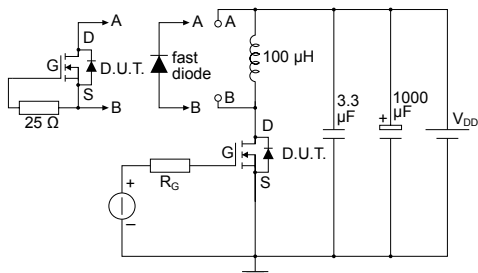
### 3 Test circuits

**Figure 11. Test circuit for resistive load switching times**


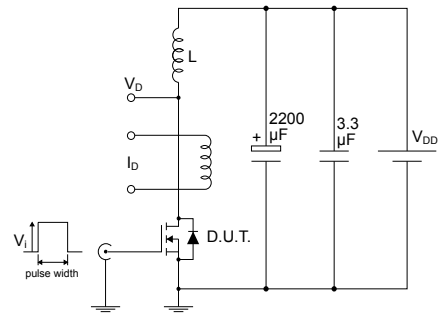
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**Figure 12. Test circuit for gate charge behavior**


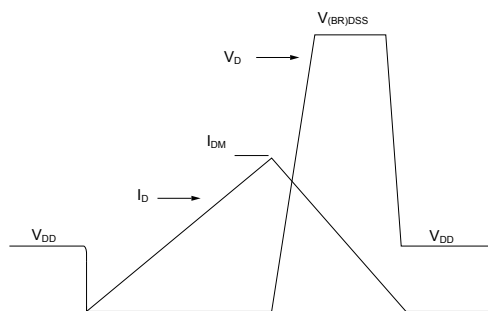
AM01469v1

**Figure 13. Test circuit for inductive load switching and diode recovery times**


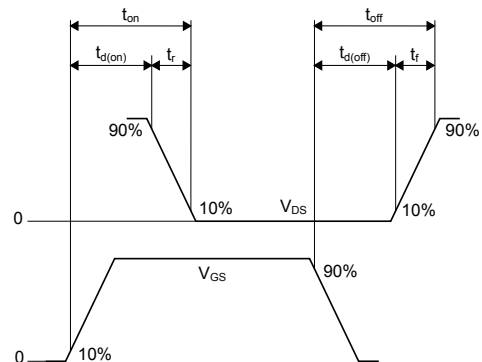
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**Figure 14. Unclamped inductive load test circuit**


AM01471v1

**Figure 15. Unclamped inductive waveform**


AM01472v1

**Figure 16. Switching time waveform**


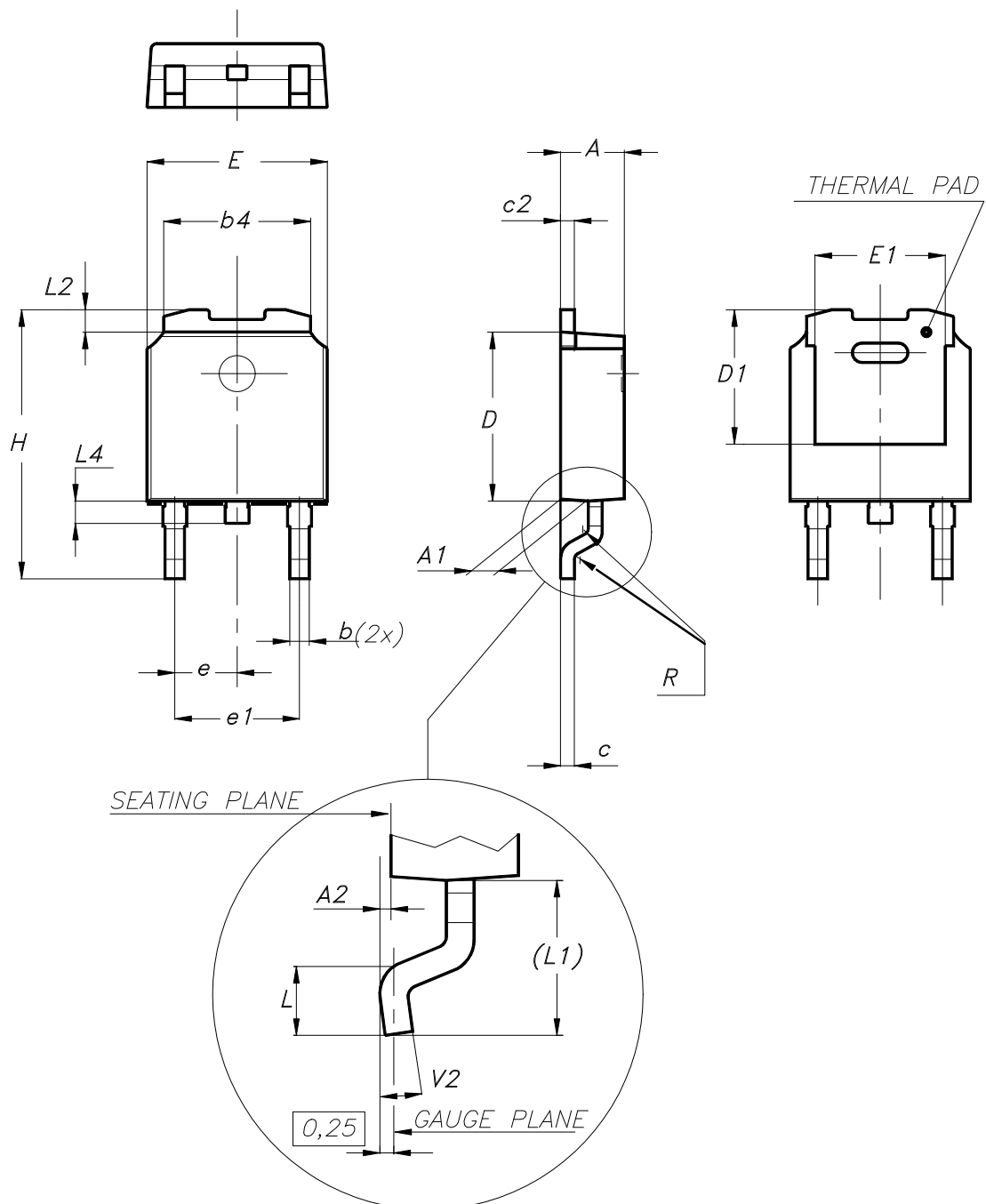
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 DPAK (TO-252) package information

Figure 17. DPAK (TO-252) type A package outline

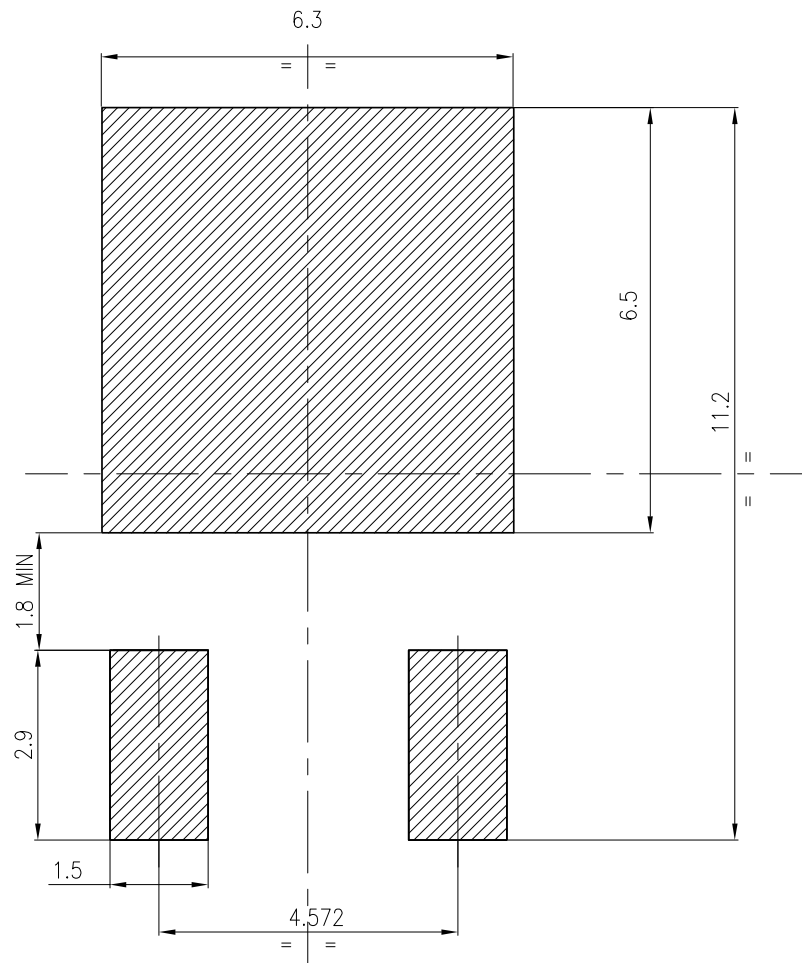




**Table 6. DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

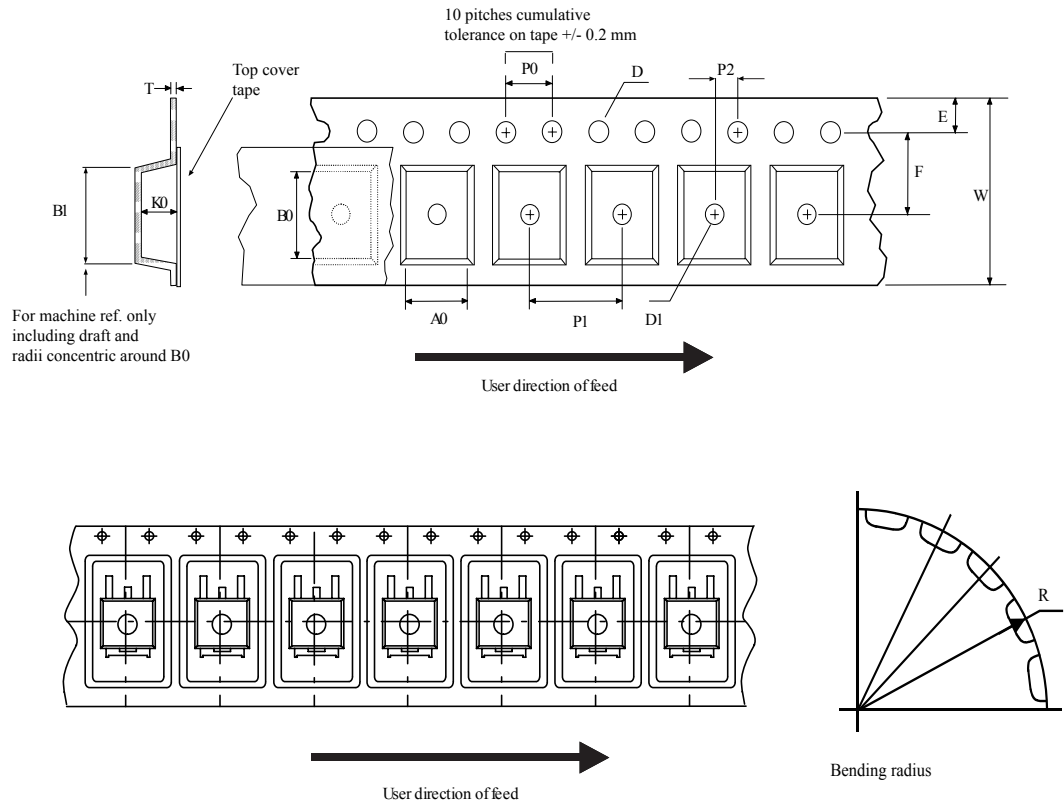
Figure 18. DPAK (TO-252) recommended footprint (dimensions are in mm)



FP\_0068772\_31

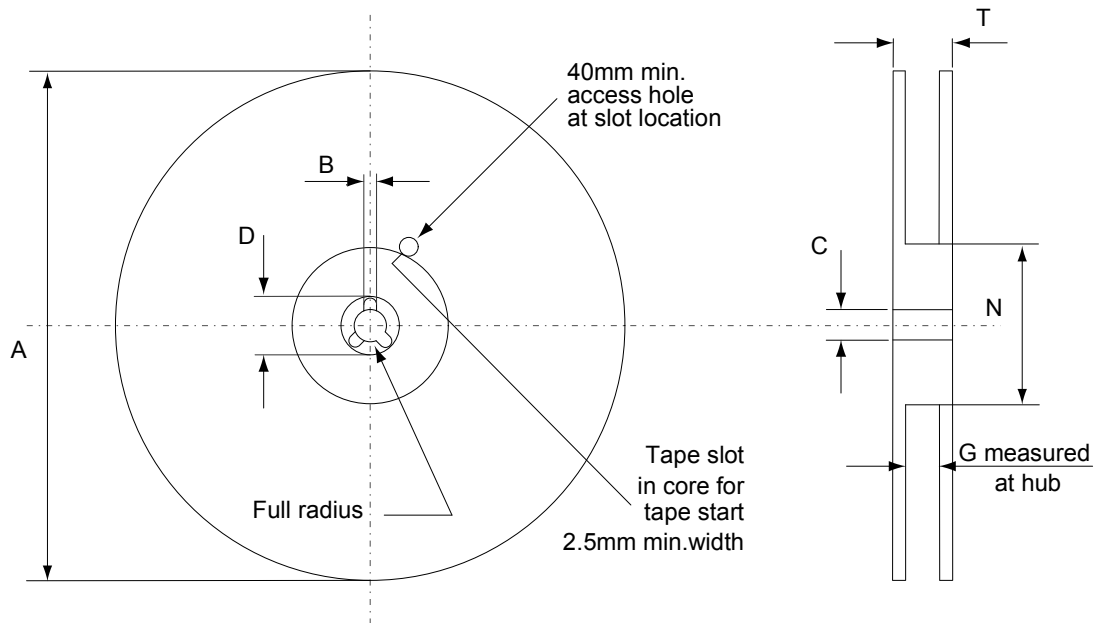
## 4.2 DPAK (TO-252) packing information

Figure 19. DPAK (TO-252) tape outline



AM08852v1

**Figure 20. DPAK (TO-252) reel outline**



AM06038v1

**Table 7. DPAK (TO-252) tape and reel mechanical data**

Dim.	Tape		Dim.	Reel	
	mm			mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1		Base qty.	2500
P1	7.9	8.1		Bulk qty.	2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

## Revision history

**Table 8. Document revision history**

Date	Revision	Changes
19-Apr-2005	2	Added package IPAK
08-Jun-2006	3	Graphical updates
03-Jul-2006	4	New template, no content change
29-Apr-2022	5	The part number STD20NF06L-1 has been removed and the document has been updated accordingly.

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